

## SBS 1.1-COMPLIANT GAS GAUGE ENABLED WITH IMPEDANCE TRACK™ TECHNOLOGY FOR USE WITH THE bq29330

### FEATURES

- Next Generation Patented Impedance Track™ Technology accurately Measures Available Charge in Li-Ion and Li-Polymer Batteries
- Better than 1% Error Over Lifetime of the Battery
- Instant Accuracy – No Learning Cycle Required
- Supports the Smart Battery Specification SBS V1.1
- Powerful 8-Bit RISC CPU With Ultra-Low Power Modes
- Works With the TI bq29330 Analog Front-End (AFE) Protection IC to Provide Complete Pack Electronics Solution
- Full Array of Programmable Protection Features
  - Voltage, Current and Temperature
- Fully Integrated High Accurate Clock
- Flexible Configuration for 2 to 4 Series Li-Ion and Li-Polymer Cells
- Integrated Field Programmable FLASH Memory Eliminates the Need for External Configuration Memory
- Smart Battery Charger Control Feature
- Two 16-Bit Delta-Sigma Converter
  - Accurate Voltage and Temperature Measurements
  - Integrating Coloumb Counter for Charge Flow
    - Better Than 0.65 nVh of Resolution
    - Self-Calibrating
- Supports SHA-1 Authentication
- 20-Pin TSSOP (PW)

### APPLICATIONS

- Notebook PCs
- Medical and Test Equipment
- Portable Instrumentation

### DESCRIPTION

The bq20z70-V110 SBS-compliant gas gauge IC, incorporating patented Impedance Track™ technology, is designed for battery-pack or in-system installation. The bq20z70-V110 measures and maintains an accurate record of available charge in Li-ion or Li-polymer batteries using its integrated high-performance analog peripherals. The bq20z70-V110 monitors capacity change, battery impedance, open-circuit voltage, and other critical parameters of the battery pack, and reports the information to the system host controller over a serial-communication bus. It is designed to work with the bq29330 analog front-end (AFE) protection IC to maximize functionality and safety, and minimize component count and cost in smart battery circuits.

The Impedance Track technology continuously analyzes the battery impedance, resulting in superior gas-gauging accuracy. This enables remaining capacity to be calculated with discharge rate, temperature, and cell aging all accounted for during each stage of every cycle.

### AVAILABLE OPTIONS

T <sub>A</sub>	PACKAGE	
	20-PIN TSSOP (PW) Tube	20-PIN TSSOP (PW) Tape & Reel
–40°C to 85°C	bq20z70-V110PW <sup>(1)</sup>	bq20z70-V110PWR <sup>(2)</sup>

(1) A single tube quantity is 50 units.

(2) A single reel quantity is 2000 units



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

IMPEDANCE TRACK is a trademark of Texas Instruments.

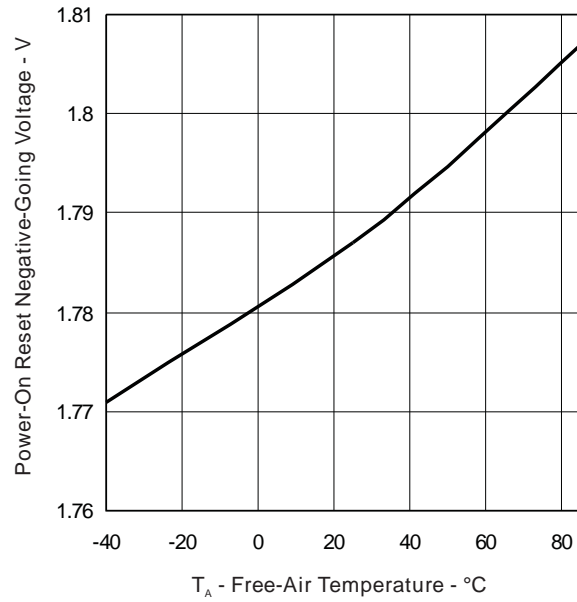


---


**ABSOLUTE MAXIMUM RATINGS**




## POWER-ON RESET

## INTEGRATING ADC (Coulomb Counter) CHARACTERISTICS

--	--	--	--

**DATA FLASH MEMORY CHARACTERISTICS**
 $V_{CC} = 2.4\text{ V to }2.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

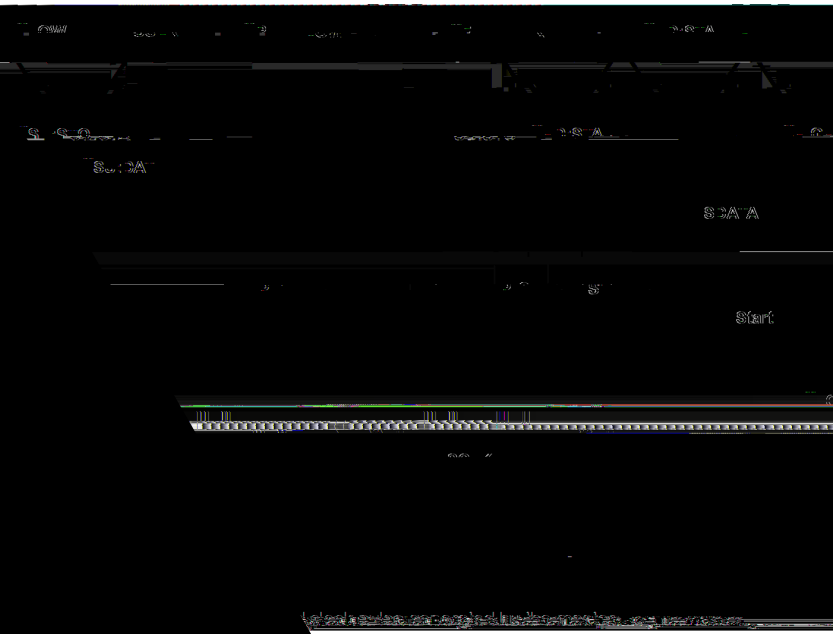
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$t_{DR}$	Data retention	See <sup>(1)</sup>	10			Years
	Flash programming write-cycles	See <sup>(1)</sup>	20,000			Cycles
$t_{(WORDPROG)}$	Word programming time	See <sup>(1)</sup>			2	ms
$I_{(DDPROG)}$	Flash-write and erase supply current	See <sup>(1)</sup>		5	10	mA

(1) Assured by design. Not production tested

**SMBus TIMING SPECIFICATIONS**

$V_{CC} = 2.4\text{ V to }2.6\text{ V}$ ,  $T_A = -40^\circ\text{C to }85^\circ\text{C}$  (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{SMB}$	SMBus operating frequency	Slave mode, SMBC 50% duty cycle				



## FEATURE SET

### Primary (1st Level) Safety Features

The bq20z70-V110 supports a wide range of battery and system protection features that can easily be configured. The primary safety features include:

- Cell over/under voltage protection
- Charge and Discharge over current
- Short Circuit
- Charge and Discharge Over temperature
- AFE Watchdog

### Secondary (2nd Level) Safety Features

The secondary safety features of the bq20z70-V110 are used to indicate more serious faults and over and

### Charge Control Features

### Gas Gauging

### Authentication

### Power Modes





## FEATURE SET (continued)

- In Sleep Mode, the bq20z70-V110 performs measurements, calculations, protection decisions and data update in adjustable time intervals. Between these intervals, the bq20z70-V110 is in a reduced power stage. The bq20z70-V110 has a wake function that enables exit from Sleep

## CONFIGURATION

### Oscillator Function

### System Present Operation

## BATTERY PARAMETER MEASUREMENTS

### Charge and Discharge Counting

### Voltage

### Current

### Auto Calibration

### Temperature

---

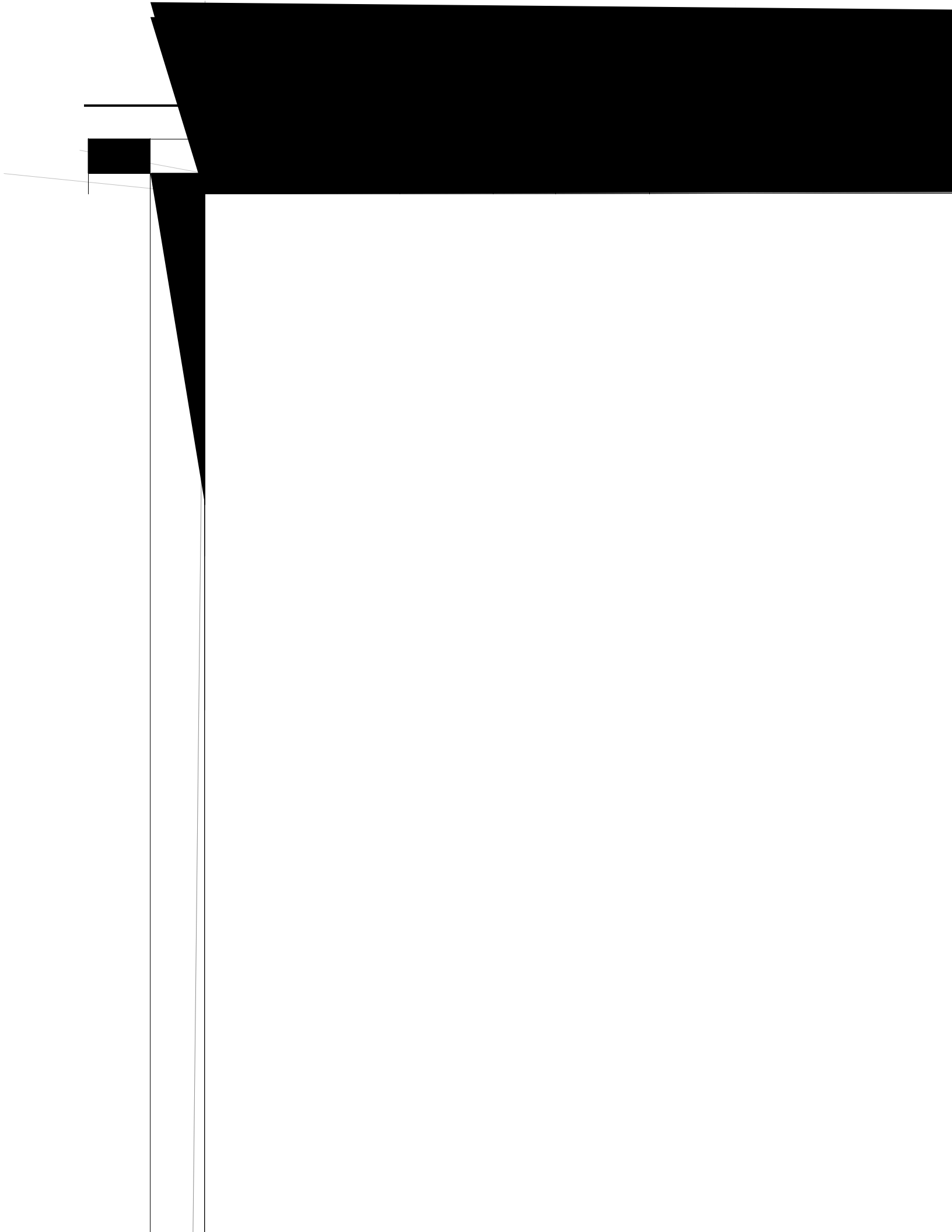
**FEATURE SET (continued)****COMMUNICATIONS**

The bq20z70-V110 uses SMBus v1.1 with Master Mode and package error checking (PEC) options per the SBS specification.

**SMBus On and Off State**

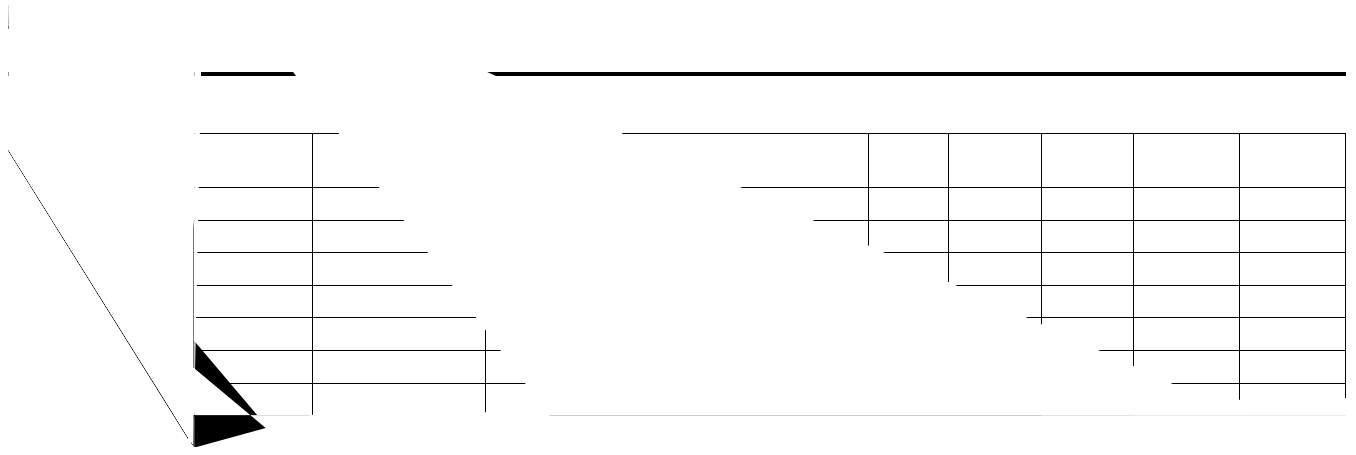
The bq20z70-V110 detects an SMBus off state when SMBC and SMBD are logic-low for  $\geq 2$  seconds. Clearing this state requires either SMBC or SMBD to transition high. Within 1 ms, the communication bus is available.

















**Table 3. DATAFLASH VALUES (continued)**

Class	Subclass ID	Subclass	Offset	Name	Data Type	Min Value	Max Value	Default Value	Units
Calibration	106	Temp Model	18	Int Coef 4	I2	-32768	32767	5754	Sec
Calibration	106	Temp Model	20	Int Min AD	I2	-32768	32767	0	Sec
Calibration	106	Temp Model	22	Int Max Temp	I2	-32768	32767	5754	Sec
Calibration	107	Current	0	Filter	U1	0	255	239	
Calibration	107	Current	1	Deadband	U1	0	255	3	mA
Calibration	107	Current	2	CC Deadband	U1	0	255	34	294 nV

### Application Schematic

The application schematic is on the following page.



## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
BQ20Z70PW-V110	NRND	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
BQ20Z70PW-V110G4	NRND	TSSOP	PW	20	70	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
BQ20Z70PWR-V110	NRND	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
BQ20Z70PWR-V110G4	NRND	TSSOP	PW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PW (R-PDSO-G20)

AAAAAAAAAA



B. This drawing is subject to change without notice.



E. Body width does not include interlead flash. Interlead flash is not included in body width.

**E. Falls within JEDEC MO-15**



DOCUMENTS  
www.ti.com



## IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible